

## AMENDMENT TO CLAIMS

1. (currently amended) A system for reducing the apparent height of a board system, comprising:
  - a carrier;
    - wherein the carrier includes a printed circuit printed on at least a first side of the carrier;
    - a component mounted on a the first side of the carrier;
    - a printed circuit board having ~~with~~ a hole, the hole being structured to accommodate the component; and
    - a solder material soldering the carrier to the printed circuit board and providing a structural bond between the carrier and the printed circuit board, at least one portion of the solder material providing an electrical coupling between the carrier and the printed circuit board,
    - wherein at least one portion of the component is maintained in the hole after the carrier is soldered to the printed circuit board;
    - a paste material disposed between the component and the first side of the carrier, the paste material having a higher melting temperature than the solder material;
    - wherein the paste material is adapted to provide a bond and an electrical coupling between the component and the carrier;
    - the paste material further adapted to provide an electrical coupling between the printed circuit of the carrier and the component; and
    - the component is electrically coupled to the printed circuit board via the paste material.

2. (Canceled)
3. (Canceled)
4. (Canceled)
5. (Canceled)
6. (Canceled)
7. (original) The system according to claim 1, wherein the solder material provides the only structural bond between the carrier and the printed circuit board.
8. (original) The system according to claim 1, wherein the solder material provides the only structural bond between the carrier and the printed circuit board.
9. (Currently Amended) A wireless communications device, comprising:
  - a duplexer;
  - a carrier board having a first side on which the duplexer is mounted using a paste material; ~~the duplexer~~;
  - a printed circuit board with a hole through which the duplexer fits; and
  - a solder material soldering the carrier board to the printed circuit board and providing a structural bond between the carrier board and the printed circuit board, wherein the paste material has a higher melting temperature than the solder material, and the duplexer is coupled electrically to the printed circuit board via the paste material, the carrier board and at least one portion of the solder material.
10. (Currently Amended) A computer system, comprising:
  - a printed circuit board;
  - a packaged integrated chip;

a carrier having a first side on which the packaged integrated chip is mounted  
using a paste material;

a the printed circuit board with a hole through which the packaged integrated chip  
fits; and

a solder material soldering the carrier and the printed circuit board, at least a  
portion of the solder material providing an electrical coupling between the carrier and the  
printed circuit board,

wherein the paste material has a higher melting temperature than the solder  
material, and the packaged integrated chip is coupled electrically to the printed circuit  
board via the paste material, the carrier board and at least one portion of the solder  
material.

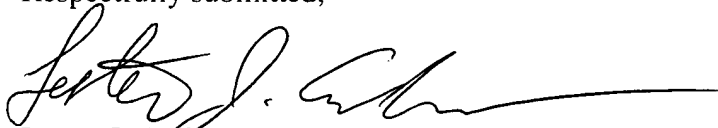
11. (Canceled)
12. (Canceled)
13. (Canceled)
14. (Canceled)
15. (Canceled)
16. (Canceled)
17. (Canceled)
18. (Canceled)
19. (Canceled)
20. (Canceled)
21. (Canceled)

22. (New) The system according to claim 1, wherein the hole extends through the printed circuit board.
23. (Canceled)
24. (Canceled)

### CONCLUSION

Applicant respectfully submits that all pending claims are now in condition for allowance. If the Examiner would find it useful, the examiner is invited to call the undersigned agent.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Lester J. Anderson", followed by a long horizontal line extending to the right.

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